# Science Robotics

## Supplementary Materials for

#### Submillimeter-scale multimaterial terrestrial robots

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*Sci. Robot.* 7, eabn0602 (2022) DOI: 10.1126/scirobotics.abn0602

#### The PDF file includes:

Supplementary Methods Figs. S1 to S38 Table S1 Legends for movies S1 to S12 References (43–62)

#### Other Supplementary Material for this manuscript includes the following:

Movies S1 to S12

### 1. Supplementary Methods

# Method S1: Step-by-step fabrication procedures for 3D robots constructed in SMA and a single layer of PI

#### Preparation of the substrate

- 1. Prepare Si wafers with Cr (sputtered, thickness: 50 nm) and SMA (sputtered, thickness:  $2.5 \ \mu m$ )
- 2. Anneal sample at 500 °C in vacuum for 30 min
- 3. Clean sample with acetone and IPA

#### Pattern the SMA

- 4. Define SMA pattern using photoresist (S1813, speed: 4000 rpm, time: 60 s, ramp: 500 rpm/s)
- 5. Etch SMA with HNO3:HF:H2O (1:1:10)
- 6. Remove photoresist with acetone

#### Pattern the PI

- 7. Spin coat PI2545 (800 rpm, 40 s; bake at 110  $^{\circ}$ C for 180 s, 150  $^{\circ}$ C for 300 s; fully cure)
- 8. Deposit Cu (thickness: 100 nm)
- 9. Define Cu pattern using photoresist (S1813, speed: 4000 rpm, time: 60 s, ramp: 500 rpm/s)
- 10. Etch Cu with copper etchant (Transene Company, Inc.; Copper Etchant CE-100; Ferric Chloride
- 25-35 wt%, Hydrochloric Acid 3-4 wt%, Water >60 wt%)
- 11. Oxygen plasma etching of PI2545 (Cu and SMA pattern serve as the etching mask)
- 12. Etch Cr with chromium etchant (Transene Company, Inc.; Chromium Etchant CEP-200; Perchloric Acid 6 wt%, Cerric Ammonium Nitrate 9 wt%, Water 75 wt%. Cu also dissolves in chromium etchant)

#### Transfer printing, buckling, and releasing

- 13. Transfer 2D precursors of robots to water soluble tape
- 14. Deposit SiO<sub>2</sub> (thickness: 100 nm) with a shadow mask to define the bonding sites for buckling
- 15. Ultraviolet ozone (UVO) treatment (intensity: 28-32 mW/cm<sup>2</sup>, wavelength: 253.7 nm) of silicone (Dragon Skin) and 2D precursors of robots for 4 min;
- 16. Transfer 2D precursors of robots onto pre-stretch silicone
- 17. Heat in the oven at 70 °C for 8 min, remove water soluble tape with water
- 18. Release prestrain to form 3D robots
- 19. Conformally deposit SiO<sub>2</sub> (thickness:  $1 \ \mu m$ ) on 3D robots and the silicone substrate
- 20. Dissolve the silicone substrate in Dynasolve
- 21. Apply sonication to remove freestanding SiO<sub>2</sub>

# Method S2: Step-by-step fabrication procedures for 3D robots constructed in SMA and a double layer of PI

#### Preparation of the substrate

- 1. Prepare Si wafers with Cr (sputtered, thickness: 50 nm) and SMA (sputtered, thickness: 2.5 µm)
- 2. Anneal sample at 500  $^\circ \rm C$  in vacuum for 30 min
- 3. Clean sample with acetone and IPA

#### Pattern the SMA

- 4. Define SMA pattern using photoresist (S1813, speed: 4000 rpm, time: 60 s, ramp: 500 rpm/s)
- 5. Etch SMA with HNO3:HF:H2O (1:1:10)
- 6. Remove photoresist with acetone

#### Pattern the 1<sup>st</sup> PI layer

7. Spin coat PI2545 (800 rpm, 40 s; bake at 110 °C for 180 s, 150 °C for 300 s; fully cure)

- 8. Deposit Cr/Au (thickness: 10 nm/100 nm)
- 9. Define Au pattern using photoresist (S1813, speed: 4000 rpm, time: 60 s, ramp: 500 rpm/s)
- 10. Etch Au with gold etchant (Transene Company, Inc.; Gold Etchant Type TFA; Iodine Complex
- 8 wt%, Potassium Iodide 21 wt%, Water 71 wt%.)
- 11. Peel off PI from the Si wafer (all materials, except the Si wafer, will attach to the PI layer)
- 12. Etch Cr with chromium etchant (Transene Company, Inc.; Chromium Etchant CEP-200; Perchloric Acid 6 wt%, Cerric Ammonium Nitrate 9 wt%, Water 75 wt%.)
- 13. Remove photoresist with acetone

#### Pattern the 2<sup>nd</sup> PI layer

- 14. Spin coat PDMS (3000 rpm, 1:10) on glass slide
- 15. Attach sample to PDMS (PI layer facing down)
- 16. Spin coat PI2545 (3000 rpm, 40 s; bake at 110 °C for 180 s, 150 °C for 300 s; fully cure)

#### Pattern the PI

- 17. Peel off PI from PDMS
- 18. Attach sample to another PDMS coated glass (1<sup>st</sup> thick PI layer facing up)
- 19. Oxygen plasma etching of PI2545 (Au/Cr and SMA pattern serve as the etching mask)
- 20. Etch Au and Cr with gold and chromium etchant

#### Transfer printing, buckling and releasing

- 21. Transfer 2D precursors of robots to water soluble tape (1<sup>st</sup> thick PI layer facing up)
- 22. Deposit SiO<sub>2</sub> (100 nm in thickness) with a shadow mask to define the bonding sites for buckling

23. UVO (intensity: 28-32 mW/cm<sup>2</sup>, wavelength: 253.7 nm) treatment of silicone (Dragon Skin) and 2D precursors of robots for 4 min;

- 24. Transfer 2D precursors of robots onto pre-stretch silicone
- 25. Heat in the oven at 70 °C for 8 min, remove water soluble tape with water
- 26. Release prestrain to form 3D robots
- 27. Conformally deposit SiO<sub>2</sub> (thickness: 1 µm) on 3D robots and the silicone substrate
- 28. Dissolve the silicone substrate (Dynasolve 230, DYNALOY)
- 29. Apply sonication to remove freestanding SiO<sub>2</sub>

#### Method S3: Step-by-step fabrication procedures for the 3D robots constructed in SMA

#### Preparation of the substrate

- 1. Prepare Si wafers with Cr (sputtered, thickness: 50 nm) and SMA (sputtered, thickness: 2.5 µm)
- 2. Anneal sample at 500 °C in vacuum for 30 min
- 3. Clean sample with acetone and IPA

#### Pattern the SMA

- 4. Define SMA pattern using photoresist (S1813, speed: 4000 rpm, time: 60 s, ramp: 500 rpm/s)
- 5. Etch SMA with HNO3:HF:H2O (1:1:10)
- 6. Remove photoresist with acetone

#### Transfer printing, buckling, and releasing

- 7. Transfer 2D precursors of robots to water soluble tape
- 8. Deposit SiO<sub>2</sub> (thickness: 100 nm) with a shadow mask to define the bonding sites for buckling
- 9. UVO treatment (intensity: 28-32 mW/cm<sup>2</sup>, wavelength: 253.7 nm) of silicone (Dragon Skin) and
- 2D precursors of robots for 4 min;
- 10. Transfer 2D precursors of robots onto pre-stretch silicone
- 11. Heat in the oven at 70 °C for 8 min, remove water soluble tape with water
- 12. Release prestrain to form 3D robots
- 13. Conformally deposit SiO<sub>2</sub> (thickness:  $1 \ \mu m$ ) on 3D robots and the silicone substrate
- 14. Dissolve the silicone substrate in Dynasolve
- 15. Apply sonication to remove freestanding  $SiO_2$

#### Method S4: Constitutive model of the shape memory alloy

The relationship between strain, stress, temperature and crystallographic phase of shape memory alloy (SMA) material in this manuscript was described by the Brinson thermo-constitutive model, as given by Ref. (*43*):

$$d\sigma = D(\varepsilon, \xi, T)d\varepsilon + \Omega(\varepsilon, \xi, T)d\xi + \Theta(\varepsilon, \xi, T)dT.$$

Here, D,  $\Omega$  and  $\Theta$  are the stiffness, phase transformation coefficient and thermal expansion coefficient of shape memory alloy. The stress can be also referred to the strain  $\varepsilon$ , martensite fractions  $\xi$  and temperature *T* as

$$\sigma - \sigma_0 = D(\xi)\varepsilon - D(\xi_0)\varepsilon_0 + \Omega(\xi)\xi - \Omega(\xi_0)\xi_0 + \Theta(T - T_0),$$

where  $\sigma_0$ ,  $\varepsilon_0$ ,  $\xi_0$  and  $T_0$  represent the values at the initial state, while  $\sigma$ ,  $\varepsilon$ ,  $\xi$  and T are the real-time state of SMA material. It is important to note that the application of a specific material restriction enforces a relationship between the stiffness and phase transformation coefficient. Considering the initial condition of  $\sigma_0 = \varepsilon_0 = \xi_0 = 0$  and final condition of  $\sigma_0 = 0$ ,  $\varepsilon = \varepsilon_L$ ,  $\xi = 1$ , the phase transformation coefficient  $\Omega$  can be given as:

$$\Omega = -D\varepsilon_L,$$

where  $\varepsilon_L$  is the maximum recoverable strain, and can be determined by the onset value that all of the original austenite are completely detwinned martensite.

For the final state ( $\sigma_0 = 0$ ,  $\xi_0 = 1$ ,  $\varepsilon_0 = \varepsilon_L$ ), the strain and stress relationship in SMA is:

$$\varepsilon = \frac{?}{\xi E_m + (1-\xi)E_a} + \varepsilon_L \xi ,$$

where  $E_m$  and  $E_a$  refer to the Young's modulus of SMA in the austenite and the martensite phase, respectively. The martensite fraction  $\xi$  during the phase transformation from martensite to austenite (heating) can be described as follows:

$$\xi = \frac{\xi_M}{2} \left( \cos \left[ \frac{\pi (T - A_S)}{A_f - A_S} - \frac{\pi \sigma}{C_A (A_f - A_S)} \right] + 1 \right).$$

And during the phase transformation from austenite to martensite (cooling), the martensite fraction  $\xi$  is

$$\xi = \frac{1-\xi_A}{2} \left( \cos \left[ \frac{\pi (T-M_f)}{M_S-M_f} - \frac{\pi \sigma}{C_M (M_S-M_f)} \right] + \frac{1+\xi_A}{2} \right),$$

where  $\xi_M$  is the minimum martensite fraction equal to  $\xi_0$ , assumed to be 1 in this case; and  $C_A$  and  $C_M$  are the dimensionless curve-fitting parameters.  $A_s$  and  $A_f$  represent the starting and finishing temperatures of the phase transformation from martensite to austenite, while  $M_s$  and  $M_f$  are the ones of the phase transformation from austenite to martensite.

# 2. Supplementary Figures

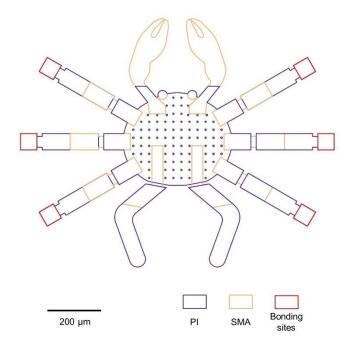
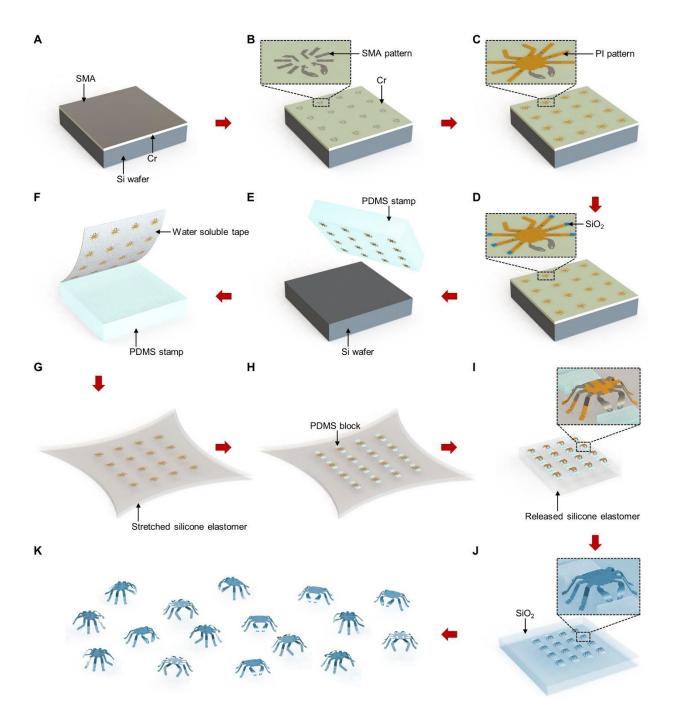
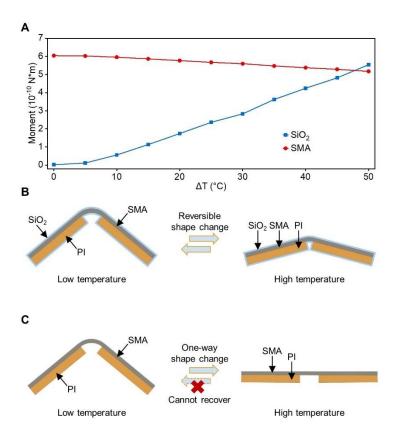


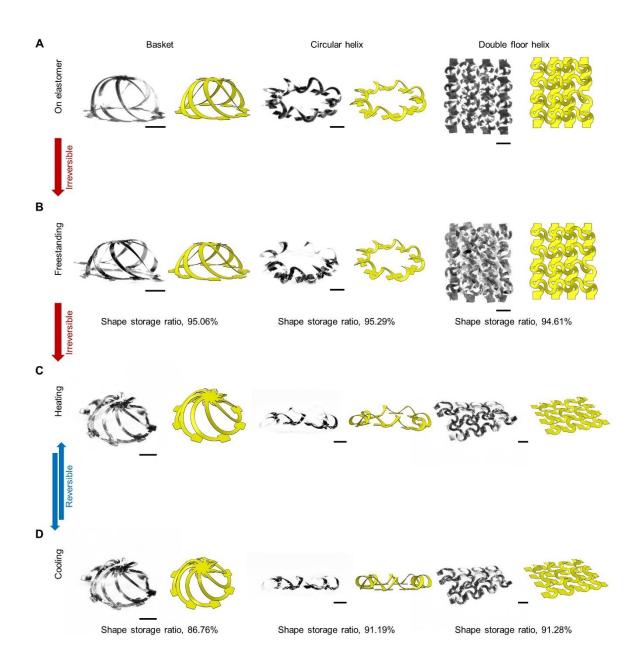
Fig. S1. 2D layout of the crab structure.



**Fig. S2. Schematic illustration of the fabrication procedures for the 3D crab.** (**A**) Si wafer with Cr and SMA. (**B**) Pattern the SMA. (**C**) Spin coat and define the PI pattern. (**D**) Deposit and pattern SiO<sub>2</sub>. (**E**) Undercut Cr and transfer the 2D precursors to a PDMS stamp. (**F**) Transfer the 2D precursors to a water soluble tape. (**G**) Transfer the 2D precursors to a prestretched elastomer. (**H**) Transfer the PDMS block. (**I**) Compressive buckling. (**J**) Conformally deposit the SiO<sub>2</sub>. (**K**) Dissolve the silicone.



**Fig. S3. Functions of the SiO**<sub>2</sub> **shell.** (**A**) Simulation results of the driving force of SMA and elastic force of SiO<sub>2</sub> shell during actuation. (**B**) Reversible shape change of the 3D robot with the SiO<sub>2</sub> shell. (**C**) One-way shape change of the 3D robot without the SiO<sub>2</sub> shell.



**Fig. S4. Experimental and FEA results of various 3D robots at different stages.** (**A**) Geometries of 3D robots on an elastomer substrate. (**B**) Geometries of freestanding 3D robots after release from the elastomer. (**C**) Geometries of freestanding 3D robots under global heating. (**D**) Geometries of freestanding 3D robots after cooling to room temperature. Scale bars, 200 µm.

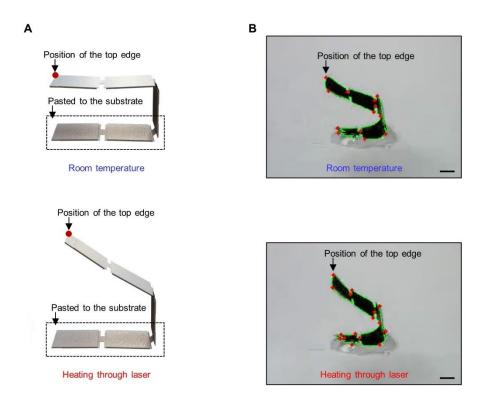


Fig. S5. Stability of reversible actuation. (A) Schematic illustration of the setup. (B) Optical image of the 3D ribbon pasted to the substrate, with detected edges (green lines) and nodes (red dots). Scale bars,  $200 \mu m$ .

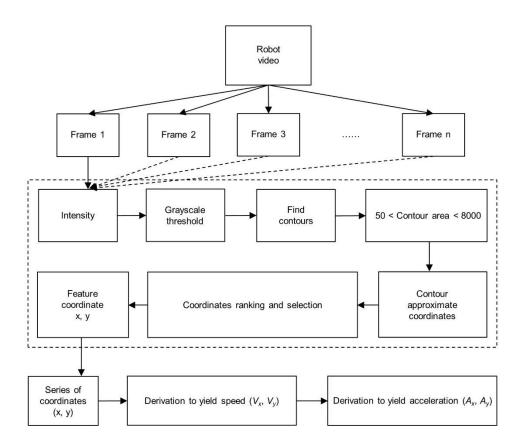
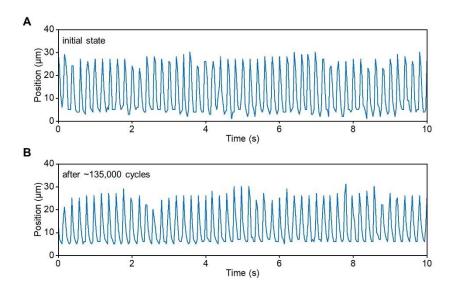
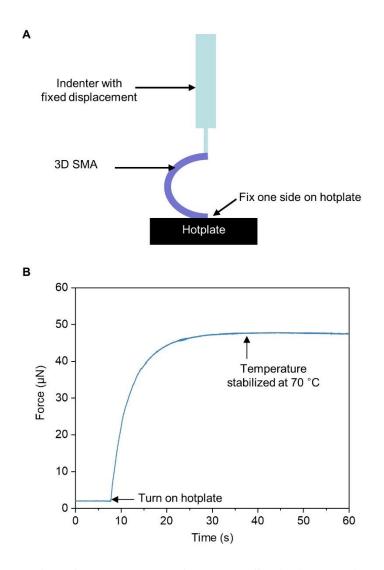


Fig. S6. Algorithm to calculate the position, speed, and acceleration of robots from video recordings.



**Fig. S7. Stability of the 3D ribbon under cyclic heating and cooling.** (**A**) Position of the top edge of the 3D ribbon at the initial state. (**B**) Position of the top edge of the 3D ribbon after ~135,000 cycles.



**Fig. S8. Measurement of the force generated from a 3D SMA ribbon.** (A) Schematic illustration of the testing setup. (B) Force as a function of time during heating.

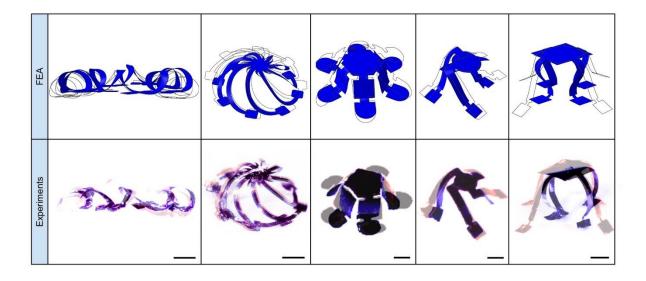
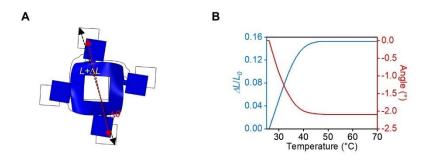


Fig. S9. Superimposed images of various 3D robotic structures. Top: FEA results; images with blue color and black lines correspond to 3D geometries at room temperature and ~100 °C, respectively. Bottom: experimental results; images colorized with blue and red colors correspond to 3D geometries at room temperature and elevated temperature (~100 °C), respectively. Scale bars, 200  $\mu$ m.



**Fig. S10. FEA results of the displacements and twisting angles of a representative 3D robot.** (A) Schematic illustration. (B) Displacements and twisting angles at different temperatures.

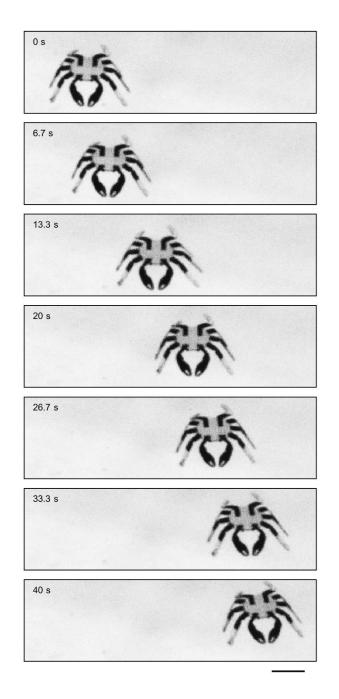
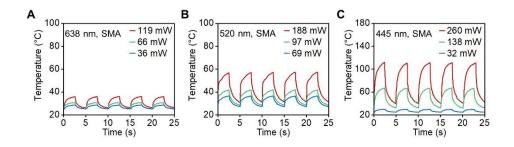


Fig. S11. Optical images of a 3D crab structure during laser-scanning at a frequency of 4 Hz. Scale bar, 500  $\mu m.$ 



**Fig. S12. Time-domain temperature responses of the planar SMA structure to laser irradiation at different wavelengths.** (A) 638 nm, (B) 520 nm, and (C) 445 nm wavelengths. The laser scanning frequency and duty cycle are 0.2 Hz and 50% (square wave), respectively.

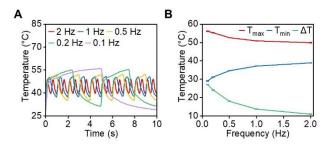
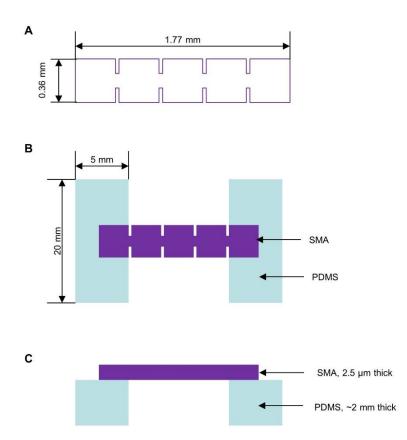
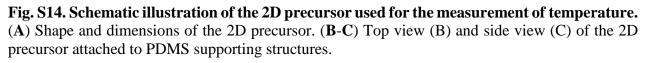


Fig. S13. Temperatures of a planar, suspended SMA ribbon under laser irradiation at different frequencies. (A) Time-domain temperature response. (B) Maximum temperature, minimum temperature, and temperature difference as a function of frequencies. Wavelength: 520 nm; power: 188 mW; duty cycle: 50% square wave.





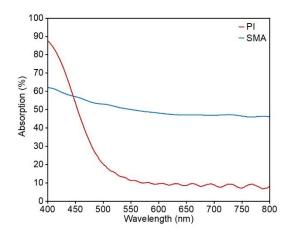


Fig. S15. Absorption spectrum of SMA (~2.5 µm in thickness) and PI (~8 µm in thickness).

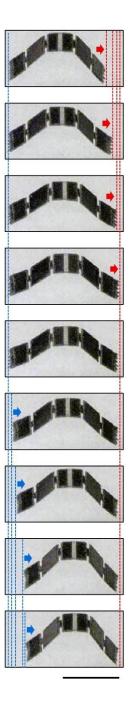


Fig. S16. Optical images showing the asynchronous movement of the left and right ends of a 3D ribbon during laser-scanning at a frequency of 0.1 Hz. Scale bar, 500  $\mu$ m. Frame interval: 0.3 s.

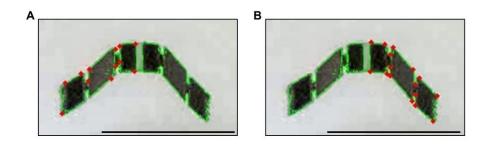


Fig. S17. Edges (green lines) and nodes (red dots) of the 3D ribbon detected from the algorithm. (A) Left part. (B) Right part. Scale bars, 1 mm.

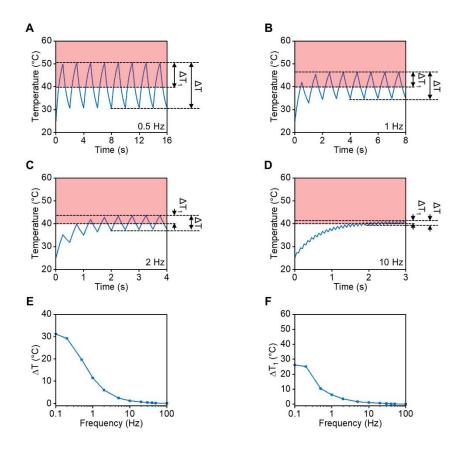


Fig. S18. FEA results of the temperature on the 3D ribbon structure. (A-D), Time-domain temperature curves at laser scanning frequencies of 0.5 (A), 1 (B), 2 (C), and 10 Hz (D). The temperature that triggers the phase transition of the SMA and the temperature above which the phase transition ceases are set to 40 °C and 75 °C, respectively. Therefore, only temperature changes between 40 to 75 °C (indicated with red background in (A-D)) are effective (defined as  $\Delta T_1$ ). (E)  $\Delta T$  at different laser scanning frequencies. (F)  $\Delta T_1$  (i.e. effective  $\Delta T$ ) at different laser scanning frequencies.

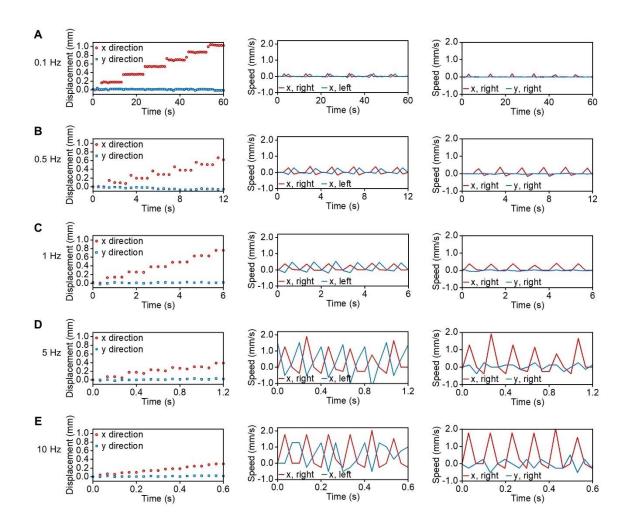


Fig. S19. Additional results of displacements and speeds of a ribbon robot under different laser-scanning frequencies. (A) 0.1 Hz. (B) 0.5 Hz. (C) 1 Hz. (D) 5 Hz. (E) 10 Hz.

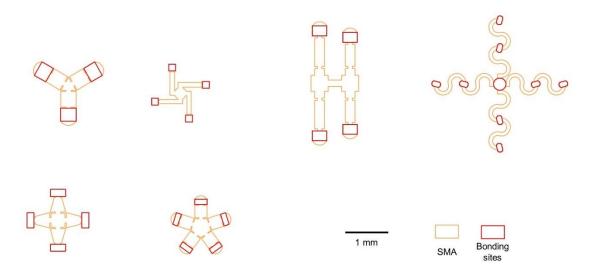


Fig. S20. 2D layouts of robots constructed in SMA.

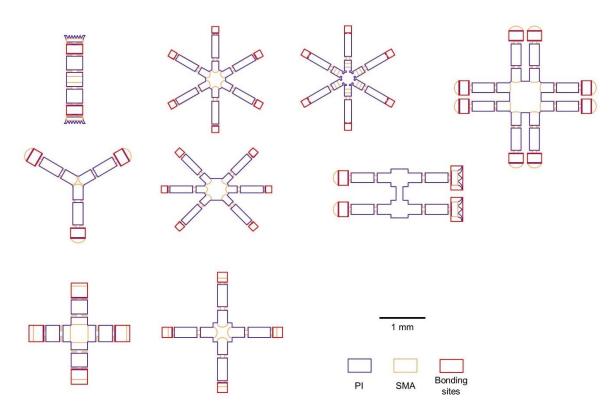


Fig. S21. 2D layouts of robots constructed in PI and SMA.

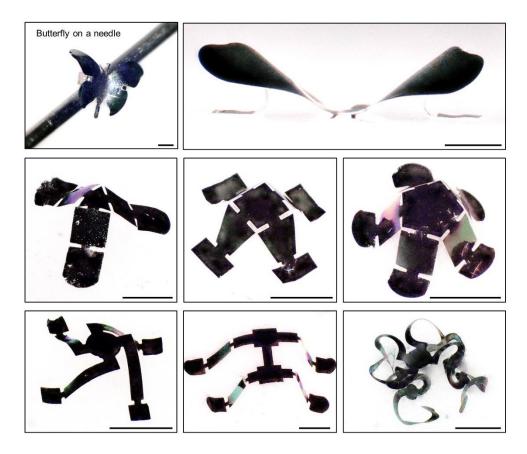


Fig. S22. Optical images of various robots constructed in SMA. Scale bars, 500  $\mu$ m.

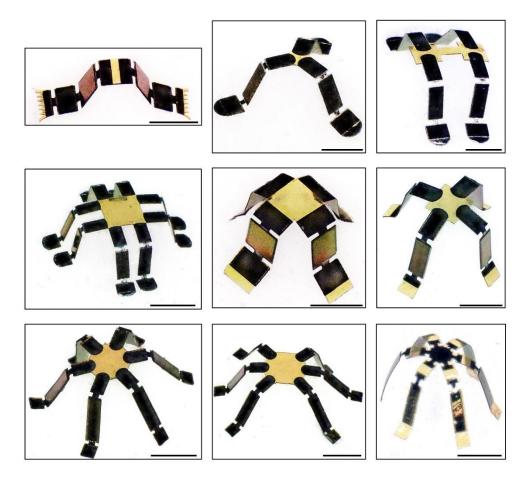


Fig. S23. Optical images of various robots constructed in SMA and PI. Scale bars, 500  $\mu m.$ 

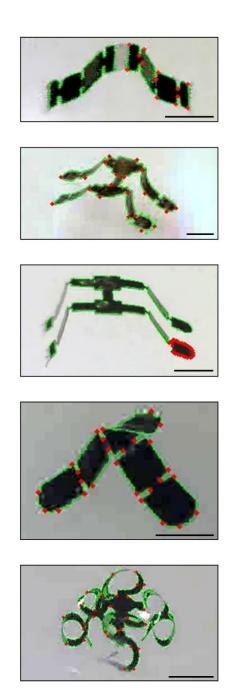
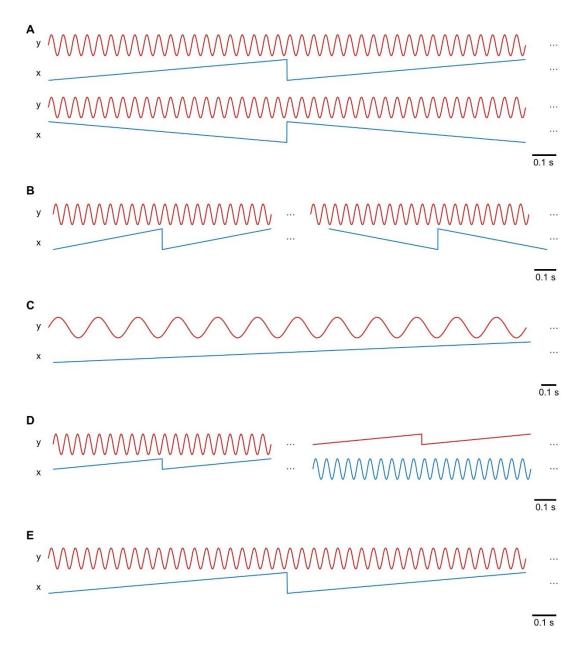
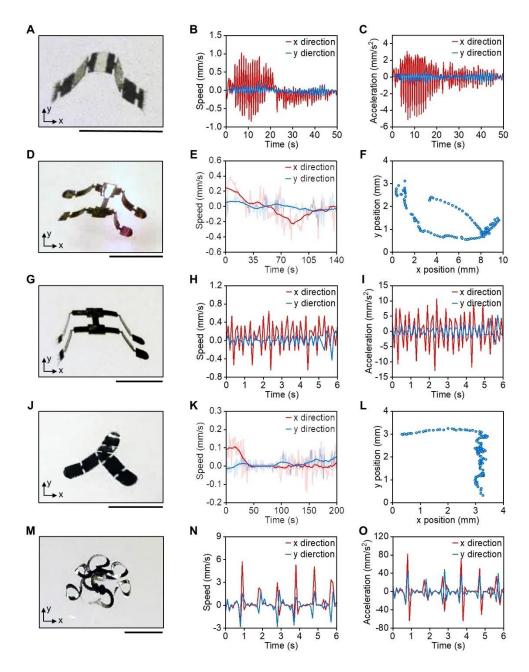


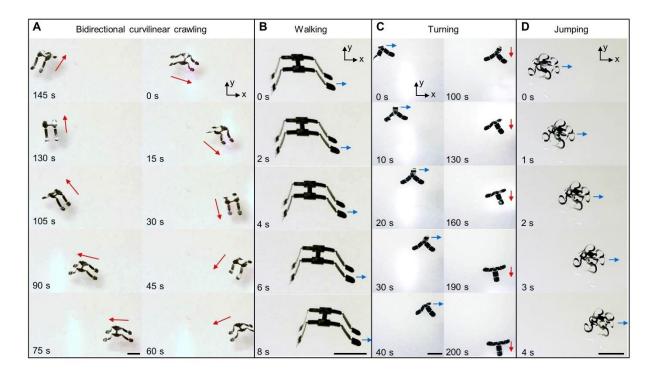
Fig. S24. Edges (green lines) and nodes (red dots) of different 3D robots detected from the algorithm. Scale bars,  $500 \ \mu m$ .



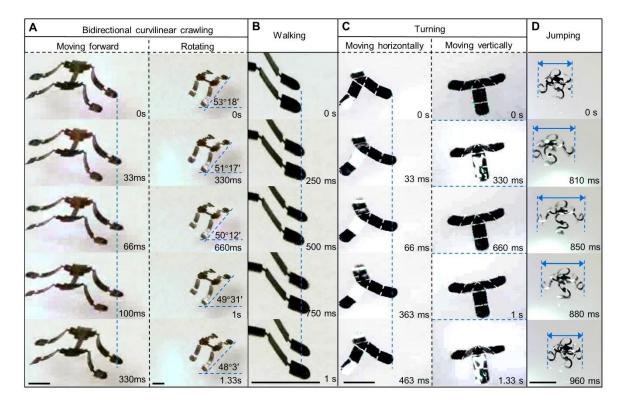
**Fig. S25. Electric signals applied to the 2-axis galvo to control the trajectories of the laser.** (A) Bidirectional linear crawling. (B) Bidirectional curvilinear crawling. (C) Walking. (D) Turning. (E) Jumping.



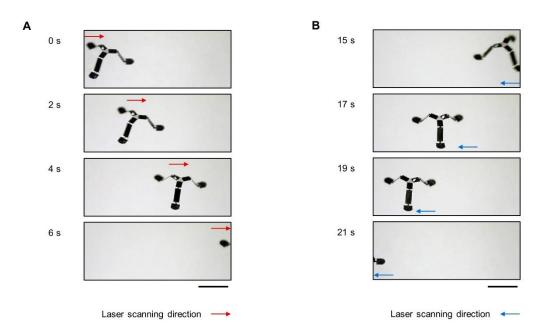
**Fig. S26.** Additional results of 3D robots with various modes of locomotion. (A-C), Bidirectional linear crawling: optical image (A), speed (B) and acceleration (C) along x and y directions. (D-F), Bidirectional curvilinear crawling: optical image (D), speed (E) and trajectory (F) along x and y directions. (G-I), Walking: optical image (G), speed (H) and acceleration (I) along x and y directions. (J-L), Turning: optical image (J), speed (K) and trajectory (L) along x and y directions. (M-O), Jumping: optical image (M), speed (N) and acceleration (O) along x and y directions. Light red and blue curves in (K) and (N) indicate speeds obtained directly from the algorithm. Dark red and blue curves in (E) and (K) indicate speeds after moving average with a window size of 25. Scale bars, 1 mm.



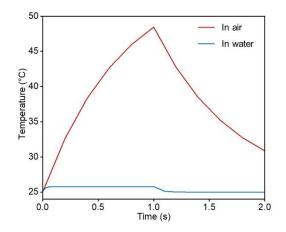
**Fig. S27.** Positions of robots with various modes of locomotions at different time points. (A) Bidirectional curvilinear crawling. (B) Walking. (C) Turning. (D) Jumping. Scale bars, 1 mm.



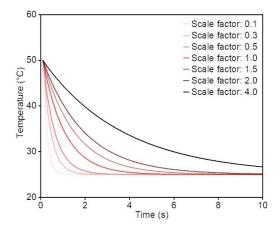
**Fig. S28. Optical images robots with various modes of locomotion at different time points.** (A) Bidirectional curvilinear crawling. (B) Walking. (C) Turning. (D) Jumping. Scale bars, 1 mm.



**Fig. S29. Optical images of a robot operated on the surface of water under laser scanning.** (A) From 0 to 6 s, the laser scans from left to right. (B) From 15 to 21 s, the laser scans from right to left. Scale bars, 1 mm.



**Fig. S30. FEA results of the temperature increase of a robot under laser irradiation.** Wavelength: 520 nm, power: 188 mW, spot size: 2.5 mm.



**Fig. S31. Dependence of cooling rate on the dimensions of the 3D robot (FEA).** Scale factor of 1.0 corresponds to the dimension of the 3D robots in Fig. 2D.

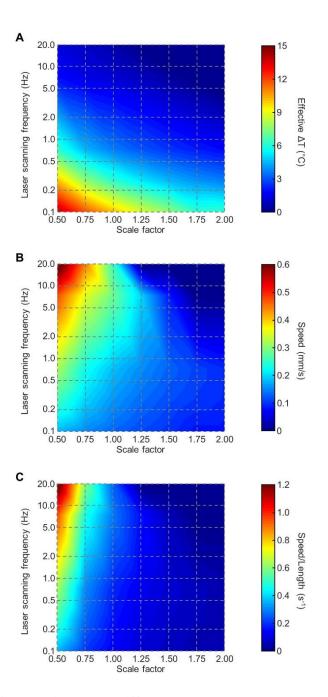
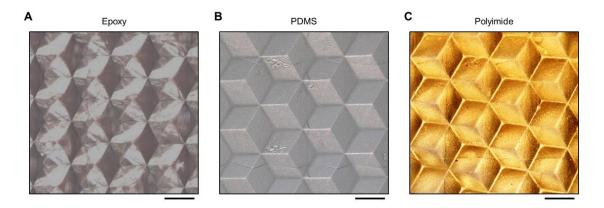


Fig. S32. FEA results of a 3D ribbon at different scales and laser scanning frequencies. (A) Effective change in temperature (effective  $\Delta T$ ). (B) Speed. (C) Speed per body length. Scale factor of 1 corresponds to the 3D ribbon shown in Fig. 2. Data at the intersections of the grey dashed lines are from simulation. Data in other areas are from interpolation.



**Fig. S33. Optical images of the retroreflector.** (**A**) Printed mold in epoxy. (**B**) PDMS structure replicated from the epoxy mold. (**C**) PI structure replicated from the PDMS structure. Scale bars, 100 μm.

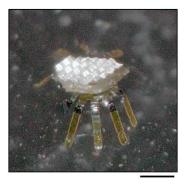
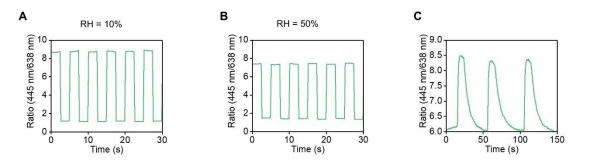
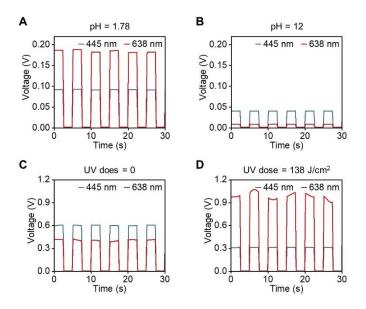


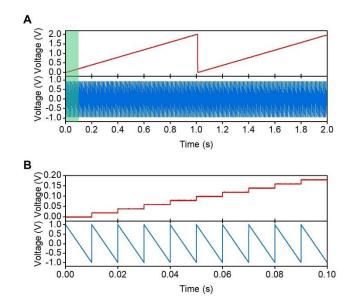
Fig. S34. Optical image of the retroreflector integrated on a robot. Scale bar, 500 µm.



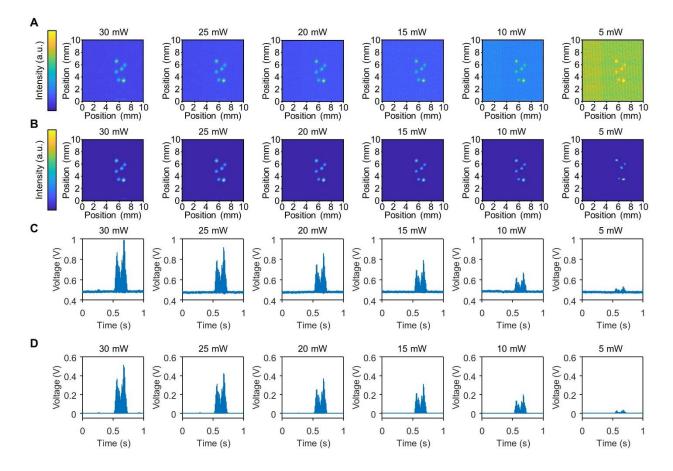
**Fig. S35. Additional testing results of the humidity sensor.** (**A-B**) Ratio between the voltages of the photodetectors for blue and red lasers at RH of 10% (A) and 50% (B). A shutter modulates the laser illumination at a frequency of 0.2 Hz. (**C**) Ratio between the voltages of the photodetectors for blue and red lasers as RH periodically changes between 50% and 10%.



**Fig. S36. Additional testing results of the pH and UV sensor.** (A-B) Time-domain output voltages of the photodetectors for blue and red lasers at a pH of 1.78 (A) and 12 (B). (C-D) Time-domain output voltages of the photodetectors for blue and red lasers at a UV dose of 0 (C) and 138 J/cm<sup>2</sup> (D). A shutter modulates the laser illumination at a frequency of 0.2 Hz.



**Fig. S37. Input signals to the 2-axis galvo for localizing robots.** (**A**) Signal in two cycles. (**B**) Signal in 0.1 s.



**Fig. S38. Localizing six robots through laser-scanning.** (A-B) Intensities of the reflected light at different laser powers in bright (A) and dark (B) environments. (C-D), Time-domain output voltages from the photodetectors at different laser powers in bright (C) and dark (D) environments.

## **3.** Supplementary Table

#### Table S1. Key parameters of the robots shown in Fig. 4.

Ref.	Actuation	Operation	Complex 3D &	Speed	Length	Speed/Length
	mechanism	environment	multi-material?	(mm/s)	( <b>mm</b> )	(s <sup>-1</sup> )
(37)	Magnetic fields	Terrestrial	Yes	37.3	2.5	14.9
(19)	Magnetic fields	Terrestrial & aquatic	No	65.5	3.7	17.7
(44)	Magnetic fields	Terrestrial	No	250	32	7.76
(45)	Magnetic fields	Terrestrial	Yes	1.67	40	0.04
(46)*	Magnetic fields	Terrestrial	No	42	0.933	60
(47)*	Magnetic fields	Aquatic	No	0.18 0.02	0.035 0.0088	5.14 2.27
(48)*	Magnetic fields	Aquatic	No	12.5	0.3	41.7
(49)	Magnetic fields	Terrestrial	Yes	25.5	5	5.1
(50)*	Battery power	Aquatic	Yes	64	93	0.69
(51)	Battery power	Terrestrial	Yes	172	45	3.8
(3)	Battery power	Terrestrial	Yes	20	58	0.34
(52)	Battery power	Terrestrial	Yes	4900	104	47
$(52)^{(52)*}$	Battery power	Terrestrial	Yes	12	40	0.3
(53)	Chemical reactions	Aquatic	No	0.12	0.02	6
(26)*	Chemical reactions	Aquatic	Yes	1.6	1	1.6
$(20)^{(20)}$	Chemical reactions	Aquatic	No	0.005	0.025	0.2
			Yes	2.34		
(55)	Chemical reactions	Aquatic	res	2.34	3	0.78
(30)	Light exposure 532 nm, 10 <sup>8</sup> mW/cm <sup>2</sup>	Terrestrial	No	0.38	0.06	6.3
(29)	Light exposure 660 nm, 2.2×10 <sup>8</sup> mW/cm <sup>2</sup>	Terrestrial	No	0.02	0.03	0.67
(56)	Light exposure ultra-violet and white light ~1000 mW/cm <sup>2</sup>	Aquatic	No	0.142	26.3	0.0054
(57)	Light exposure 385 nm, 150 mW/cm <sup>2</sup>	Terrestrial	No	0.25	8	0.031
(58)	Light exposure 532 nm, ~70000 mW/cm <sup>2</sup>	Terrestrial	No	0.5	14.5	0.034
(59)	Light exposure 808 nm, 280 mW/cm <sup>2</sup>	Terrestrial	No	16	34	0.47
(60)	Light exposure 532 nm Up to ~4700 mW/cm <sup>2</sup>	Aquatic	No	0.3	14	0.02
(20)	Light exposure NIR light, 250 mW/cm <sup>2</sup>	Terrestrial	No	1.75	14.5	0.12
(61)	Light exposure 447 nm, 8.9 mW/cm <sup>2</sup>	Terrestrial	No	1.1×10 <sup>-4</sup>	16.5	6.7×10 <sup>-6</sup>
(22)	Light exposure 785 nm, 10000 mW/cm <sup>2</sup>	Aquatic	No	0.001	0.07	0.014
(62)	Light exposure 520 nm up to 4500 mW/cm <sup>2</sup>	Terrestrial	No	0.37	15	0.025

References marked with '\*' correspond to robots that can change directionality during movement in a controllable way.

### 4. Supplementary Movies

Movie S1. Stability of the robots.

Movie S2. Various motion modalities of the robots.

Movie S3. Selective activation of one crab structure.

Movie S4. Directional locomotion of the crab structure.

Movie S5. Edges and nodes of the ribbon structure detected by the customized algorithm.

Movie S6. Directional locomotion of the ribbon structure at different laser-scanning frequencies.

Movie S7. Robot with bidirectional linear crawling locomotion.

Movie S8. Robot with bidirectional curvilinear crawling locomotion.

Movie S9. Robot with walking locomotion.

Movie S10. Robot with turning locomotion.

Movie S11. Robot with jumping locomotion.

Movie S12. Robot operated on the surface of water.